DSW03C-ZJS
晶棒单线截断机
Silicon Ingot Single Diamond Wire Cutter

加工能力(Processing Capacity)：
单晶(Mono–crystalline)：Φ150~230mm×3pcs
最大截断长度(Max. cutting Length)：800mm

加工效率(Processing Efficiency)：
6”≤10min/刀
6”≤10min per cutting
8”≤15min/刀
8”≤15min per cutting

加工精度(Processing Accuracy):
端面平整度(End Surface Flatness)：≤0.5°
切割长度精度(Cutting Length Accuracy)：≤0.3mm

切割线规格(Cutting Wire Size):
直径(Diameter)：0.32~0.45mm
张力(Tension)：0–100N
最大装线量(Max. wire Length)：2km

晶棒单线截断机是采用金刚线切割的方式进行单晶硅棒截断加工的专用设备。该设备结构合理，加工工艺精良，可实现从上料、加工、下料等全过程的自动控制，经过该设备加工后的单晶硅棒主要应用于太阳能光伏电池领域。该设备可满足高效率、量产化、自动化的生产要求，具有较高的性价比和广阔的市场应用前景。

Silicon Ingot Single Wire Cutter is a kind of dedicated equipment which put the way of diamond wire cutting for cutting the single silicon ingot. The legitimately structure and the sophisticated technology of the equipment makes it wholly automatic during the loading, laying–off and programming, the ingot after treatment is mainly used in the field of solar pv battery. It meet the need of high efficiency, mass production, automation which makes itself obtain a brighter feature in the market.

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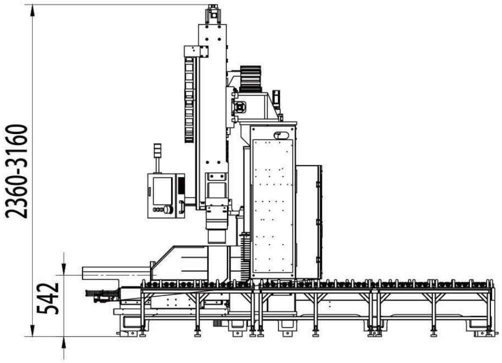
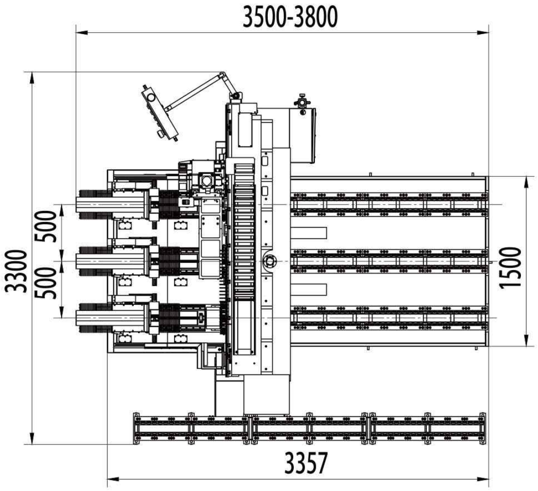


基本尺寸(Basic Size)

长(Length)：3800mm
宽(Width)：3300mm
高(Height)：3200mm
重量(Weight)：约5.8t

设备参数(Equipment Specification)

切割线运行方式(Cutting Wire Operation Mode)：往复(Reciprocating)
切割线直径(Cutting Wire Diameter)：0.32-0.45mm
切割速度(Cutting Speed)：15-20mm/min
加速时间(Acceleration Time)：5s
切割线张力(Cutting Tension)：0-100N
切割线存储量(Wire Loading Length)： 2km
工作台行程(Travel of WorkingTable)：500mm
工作台进给速度(Feed Speed of Working Table)：0.1-20mm/min



电源(Electrical)：

容量(Capacity)：20KVA
供电电源(Power Supply)：380V，50HZ

冷却水(Coolant Water)：

流量(Flow Rate)：≥15L/min
进水压力(Inlet Pressure)： 1.5 ~2.5bar
进水温度(Inlet Temperature)：24±1℃

压缩空气(Compressed Air)：

压力(Pressure)：≥5bar
流量(Flow)：≥60L/min